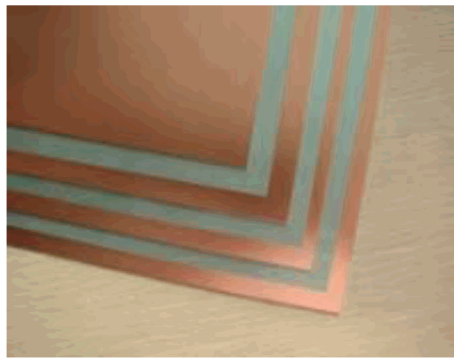


Description and Application

Aluminum base copper-clad laminate have excellent flame retardant, high mechanical strength, dimensional stability etc. Especially it has very good heat sink, electromagnetic shielding and solder float.

It's widely used for the modifier and sparker on fire for motorcycle and mobile, power LED, sound box, power supply module and acoustics shielding system etc.

Note: Chaoshun specializing in the productions of metal base copper-clad Laminates, product has been serialized, gage Comparison of homogeneous lattice, wherein the aluminum substrate type5: CCAF-01, CCAF-01-R, CCAF-04-A, CCAF-05, CCAF-06, sheet aluminum thickness 0.8mm, 1.0mm, 1.2mm, 1.5mm, 2.0mm, 3.0mm, aluminum models: 1060300350526061, Copper foil thickness is 18um, 35um, 70um, 105um, 140um. Board size: 600mm×500mm; 1200mm×500mm; 1200mm×600mm; 1200mm×600mm.



CCAF-01 Data sheet 1.5mm 35um/0 75um Dielectric layer

Test item		Company	CCAF-01 Test results
Peel Strength	Normal behavior A	N/mm	2.0
	After thermal stress		1.8
Blister test After Thermal stress		/	(260°C, 2min) No slice, No blister
Thermal resistance		°C/W	1.0
Thermal-conductive Factor		W/m·k	1.0
Flammability (A)		/	FV-0
Surface Resistivity	Normal behavior A	MΩ	5×10^7
	Constant damp heat (25degrees to 65 degrees c., RH:90%~98%, 20cycles after)		2×10^6
Volume Resistivity	Normal behavior A	MΩ·m	4×10^8
	Constant damp heat (25degrees to 65 degrees c., RH:90%~98%, 20cycles after)		5×10^7
Breakdown voltage AC (5mA leakage current)		KV	4
Dielectric constant (1MHZ)(40°C, 93%, 96h)		/	4.2
Dielectric loss factor (1MHZ)(40°C, 93%, 96h)		/	0.02
CTI		V	230